



New Multi-Functional Micro- and Nanoimprint Solution from EV Group Offers Unprecedented Flexibility for High-Volume Optical Device Manufacturing – January 21, 2022



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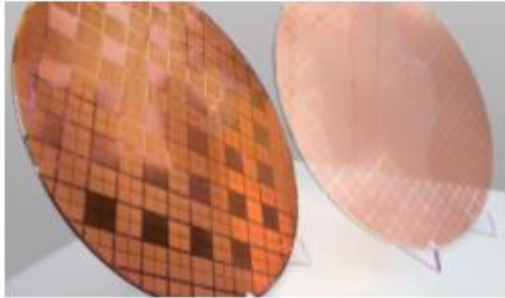
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Everything You Need to Know About Nominating Your Company for the 2022 3D InCites Awards

The 2022 3D InCites Awards process kicked off this week. This year, we are excited to partner with the International Microelectronics and Packaging Society (IMAPS) to bring you the 2022 3D InCites Awards at the 2022 Device Packaging Conference, March 7-10, 2022. Thanks to this year's Platinum Sponsors, ASE Group, EV Group, and KLA; Gold Sponsor, Evatec and YES; and Silver Sponsors, CyberOptics and Veeco. Here's everything you need to know to nominate your company for an award.

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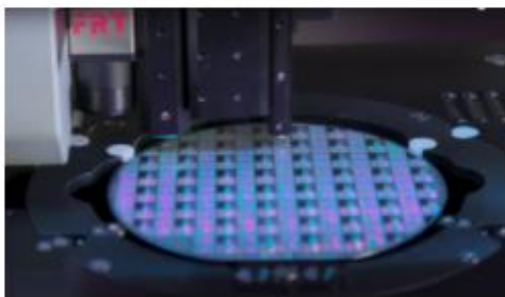


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How to Prevent High Wafer Warpage in Fan-in and Fan-out Wafer Level Packaging

This white paper discusses a low-warpage, high UPH, REACH-compliant liquid compression molding material that overcomes high wafer warpage and enables higher reliability FO WLP and FI WLP devices.



Metrology For Advanced Packaging Applications



A Conversation about Life Lessons Learned at CES 2022



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Member of the Week



As we kick off the opening of the 3D InCites Awards this week, we highlight one of last year's winners, Deca, recipient of the Herb Reiter Design Tool Provider of the Year. Deca was recognized for its Design During Manufacturing (DDM) capabilities which supports its licensees and partners in implementing Adaptive Patterning™ (AP). AP Live, a cloud-based solution that eliminates the need for dedicated on-site hardware and software, allows customers to gain early access to AP and experience its power for improving yield, scaling technologies, reducing cost, and enhancing performance. Its flagship product is the M-Series™, a rugged, fully molded fan-out wafer-level package (FOWLP) that provides exceptional reliability and quality; all in a miniaturized format. The M-Series™ FX has been designed into diverse high-volume mobile applications around the globe delivering record setting product performance.

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Company News

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Mar 7, 2022

